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(54) **METAL MESH LID MEMS PACKAGE AND METHOD**

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(71) Applicant: **Amkor Technology, Inc.**, Chandler, AZ (US)

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(72) Inventors: **Bob Shih-Wei Kuo**, Chandler, AZ (US);  
**Russell Shumway**, Mesa, AZ (US);  
**Louis B. Troche, Jr.**, Gilbert, AZ (US)

(73) Assignee: **Amkor Technology, Inc.**, Tempe, AZ (US)

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**B81B 7/00** (2006.01)  
**B81C 1/00** (2006.01)

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See application file for complete search history.

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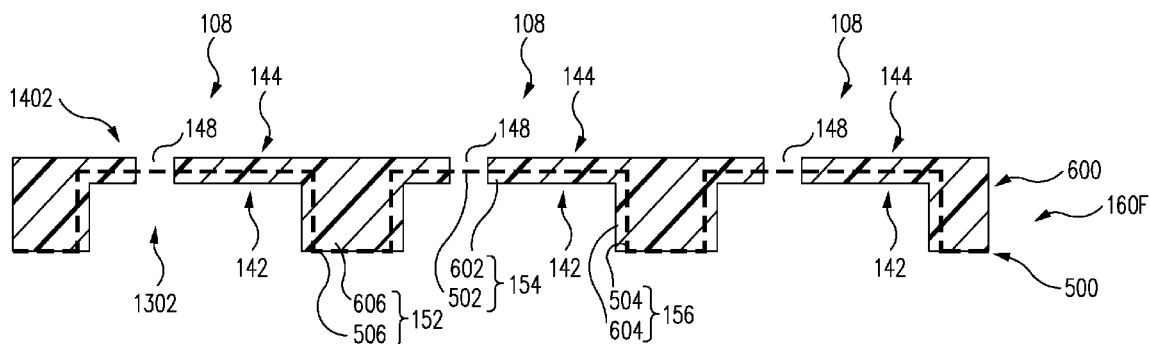
*Primary Examiner* — Fei Fei Yeung Lopez

(74) *Attorney, Agent, or Firm* — McAndrews, Held & Malloy

(57) **ABSTRACT**

A metal mesh lid MEMS package includes a substrate, a MEMS electronic component coupled to the substrate, and a metal mesh lid coupled to the substrate with a lid adhesive. The metal mesh lid includes a polymeric lid body having a top port formed therein and a metal mesh cap coupled to the lid body. The metal mesh cap covers the top port and serves as both a particulate filter and a continuous conductive shield for EMI/RF interferences. Further, the metal mesh cap provides a locking feature for the lid adhesive to maximize the attach strength of the metal mesh lid to the substrate.

**20 Claims, 9 Drawing Sheets**



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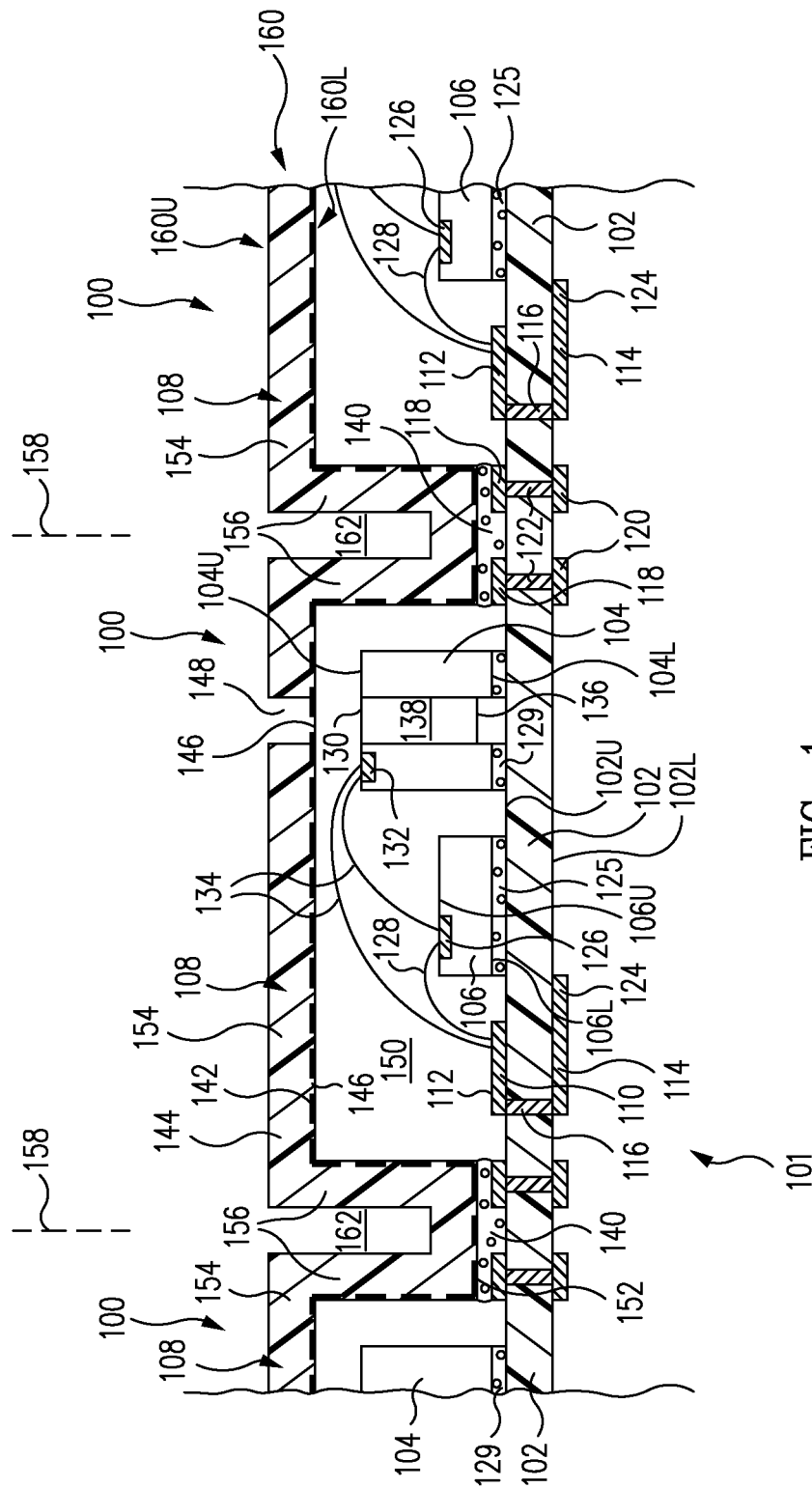


FIG. 1

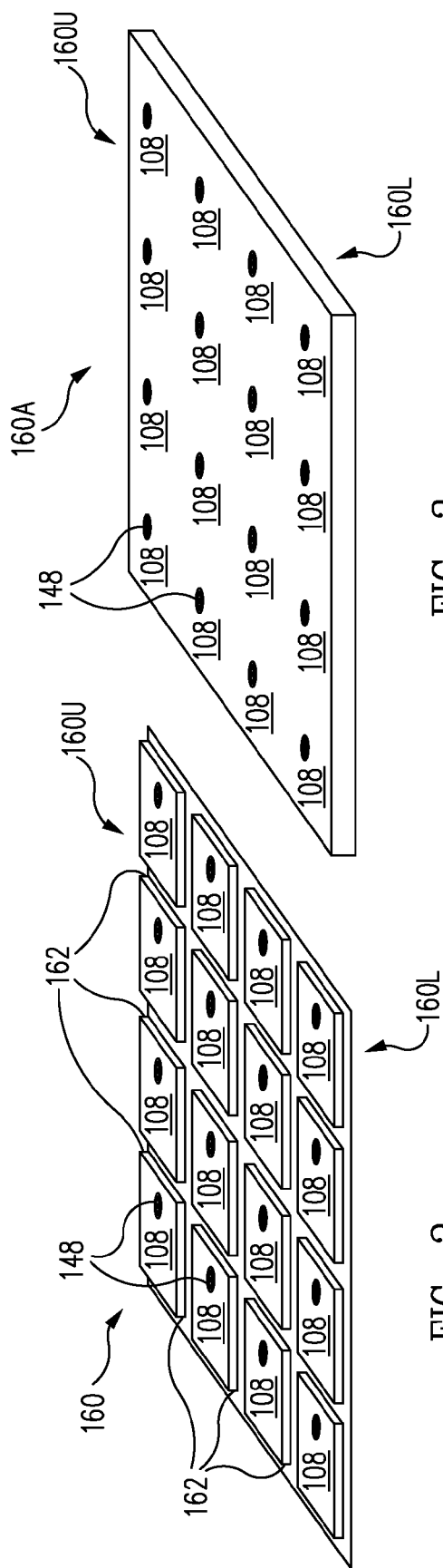


FIG. 3

FIG. 2

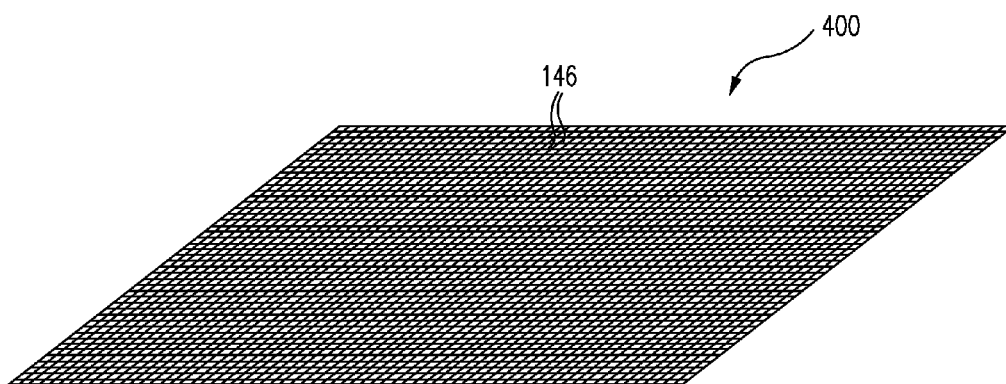


FIG. 4

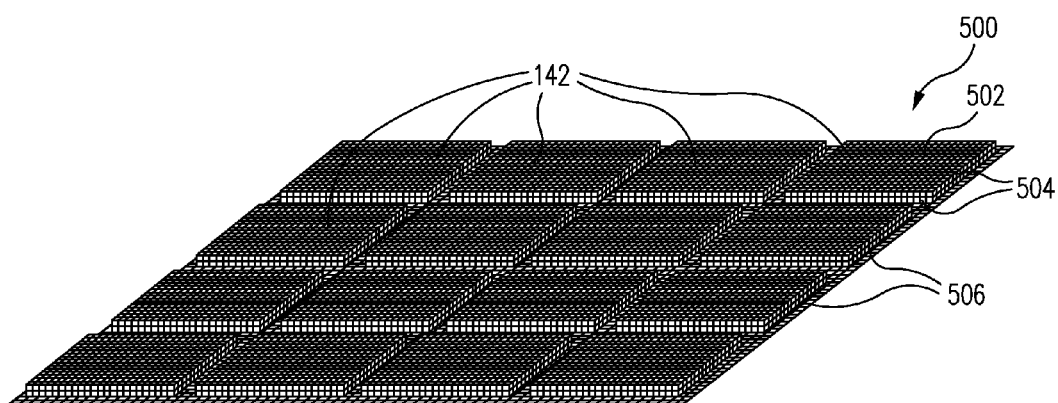
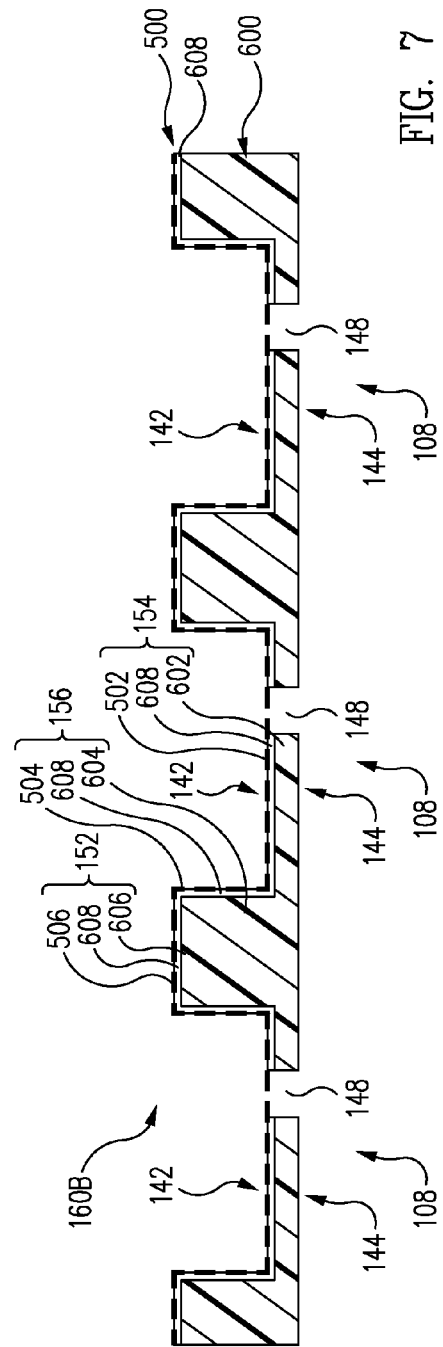
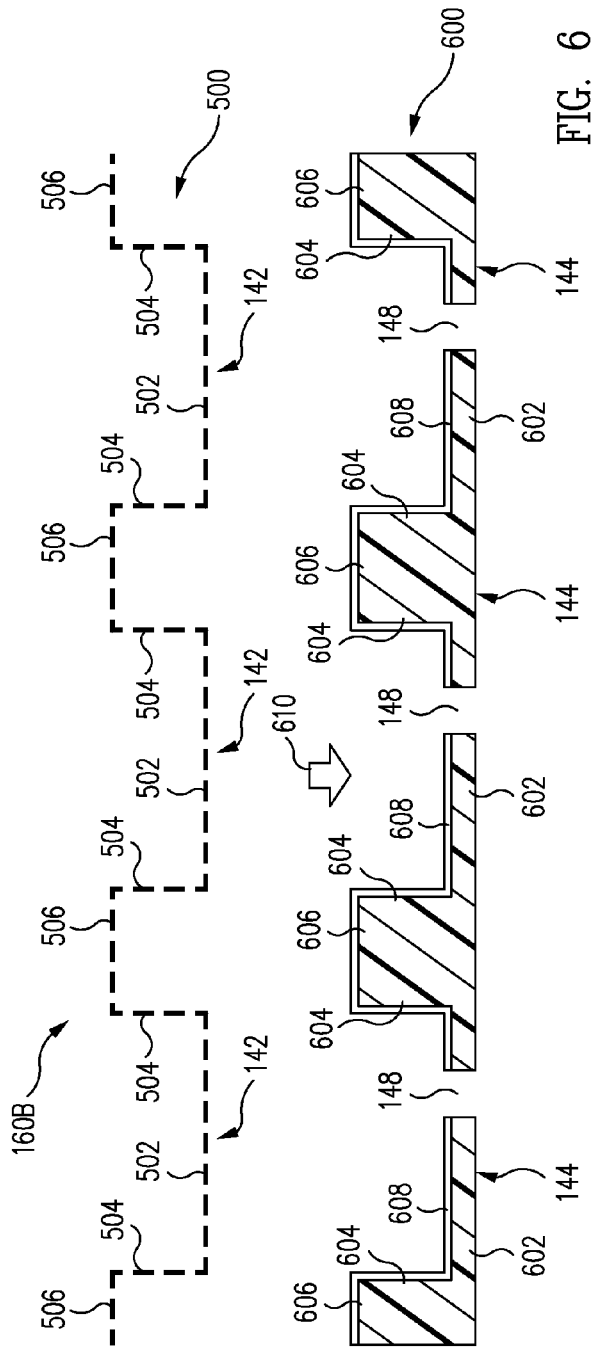


FIG. 5



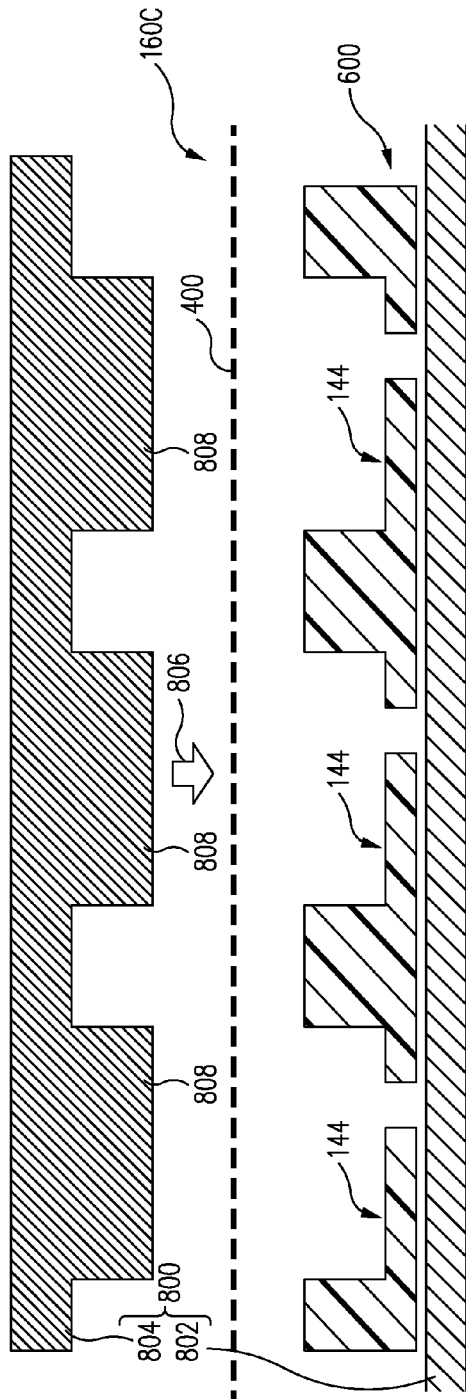


FIG. 8

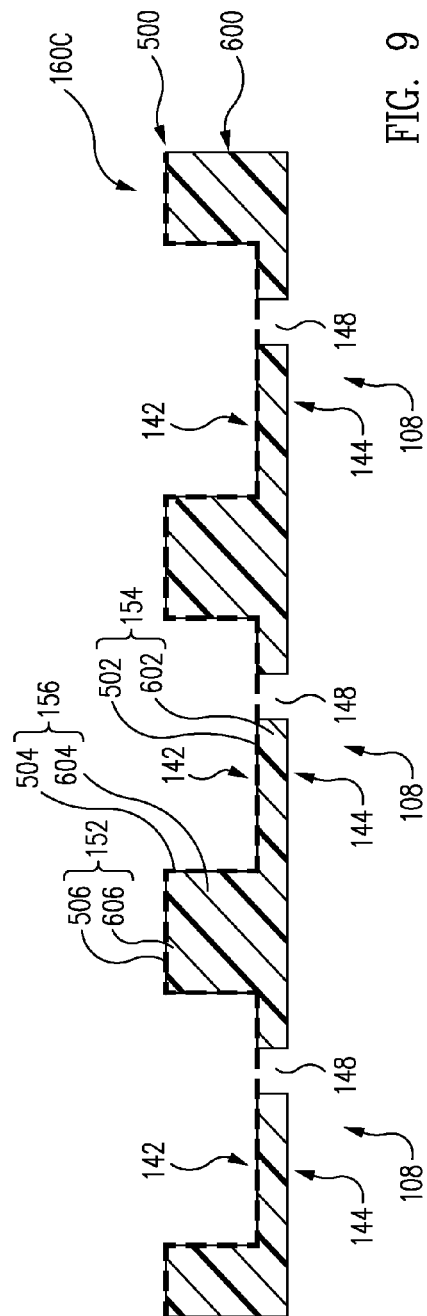


FIG. 9

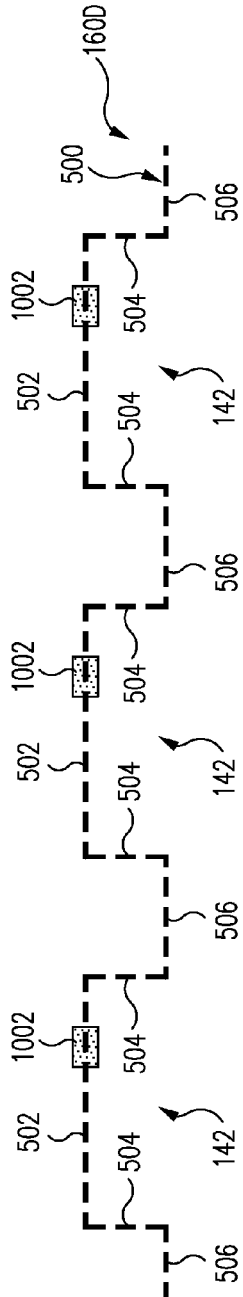


FIG. 10

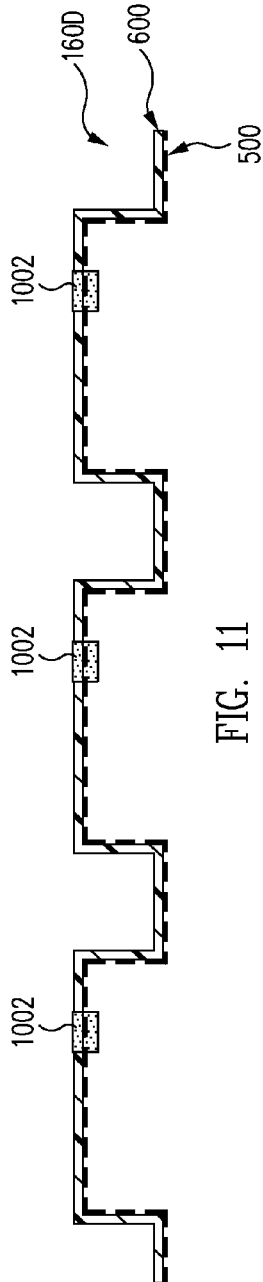


FIG. 11

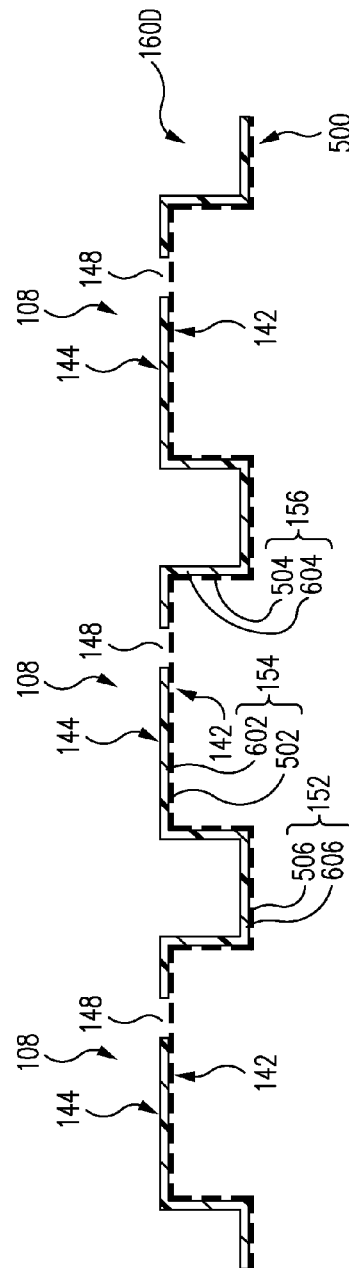


FIG. 12



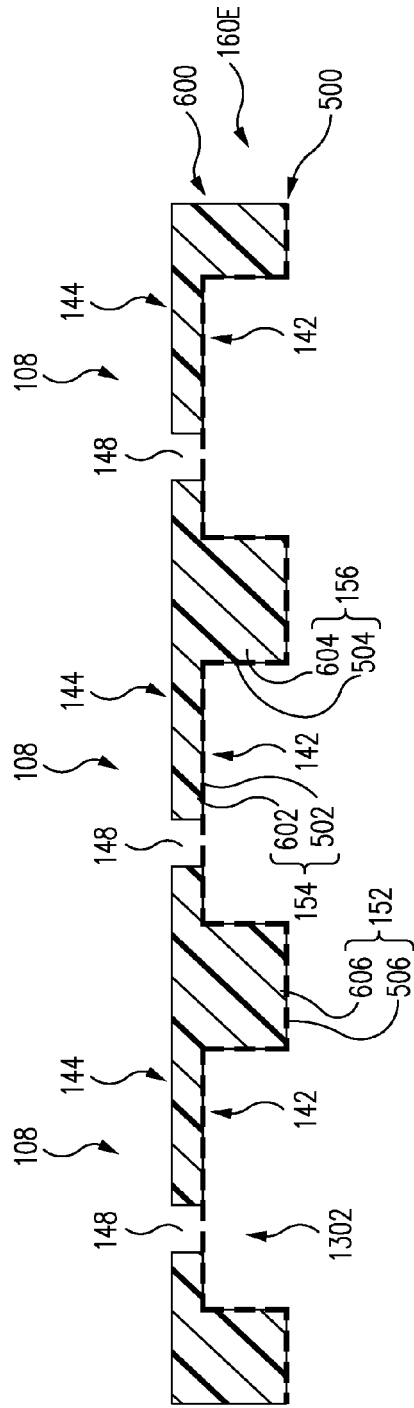


FIG. 13

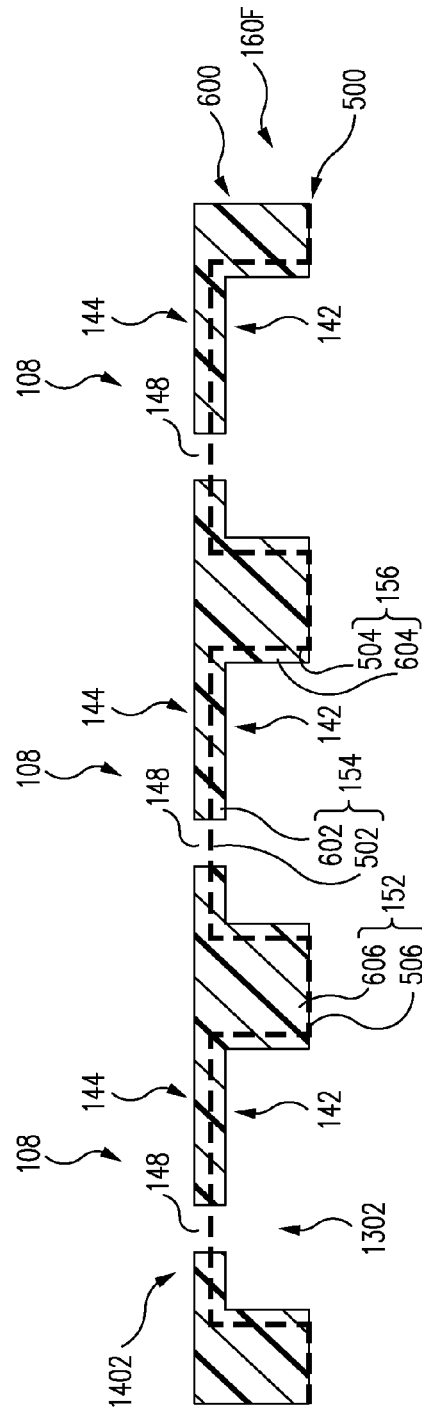


FIG. 14

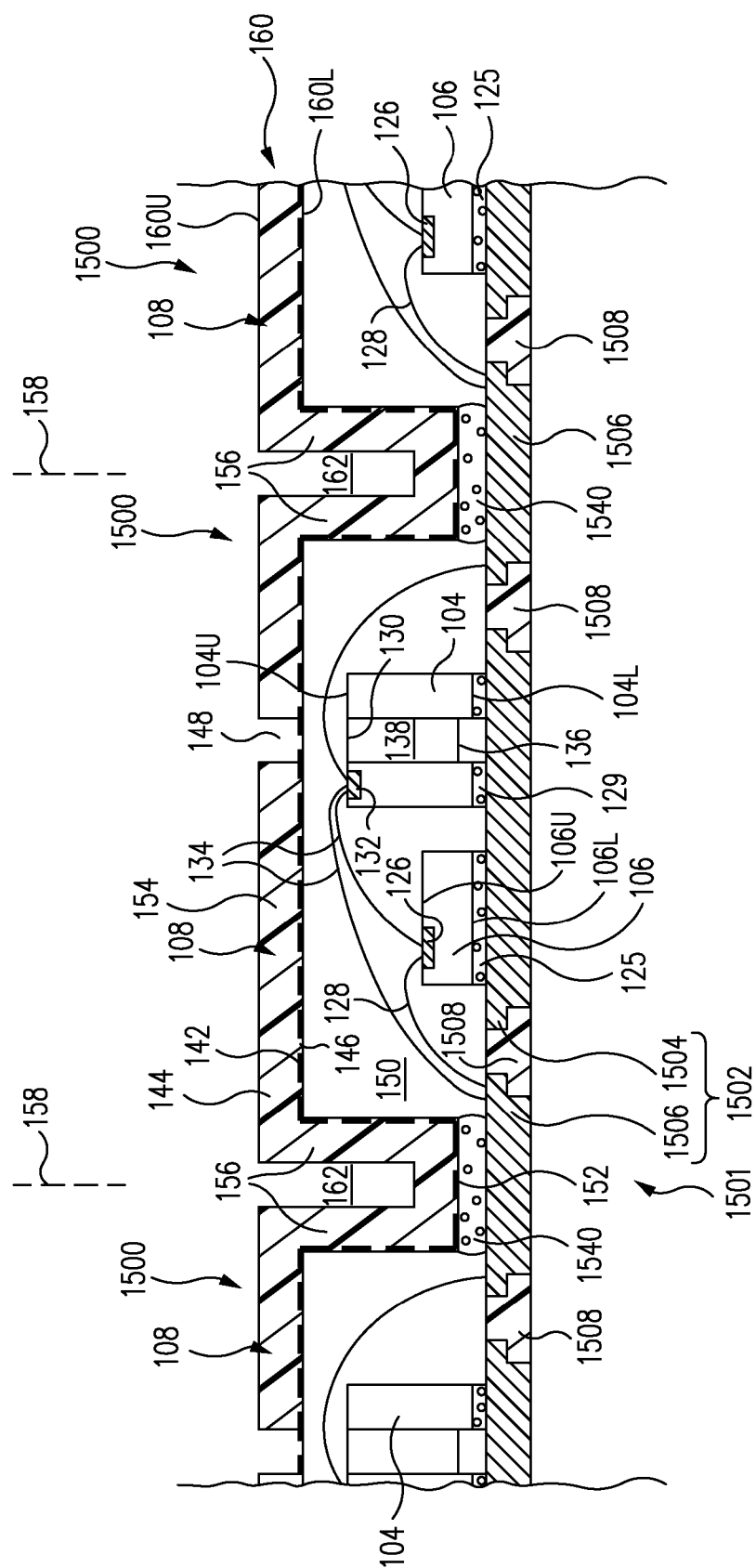


FIG. 15

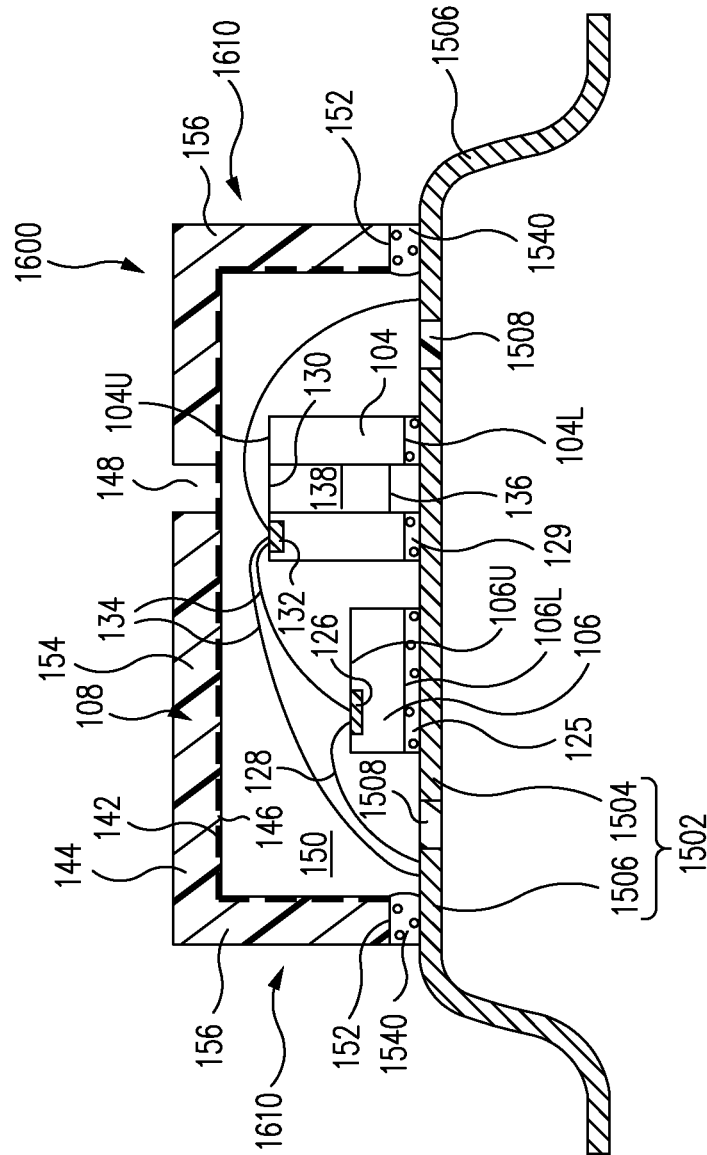


FIG. 16

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## METAL MESH LID MEMS PACKAGE AND METHOD

### RELATED APPLICATIONS

This application is a continuation of Kuo et al., U.S. patent application Ser. No. 13/096,359, filed on Apr. 28, 2011, entitled "METAL MESH LID MEMS PACKAGE AND METHOD", which is herein incorporated by reference in its entirety.

### TECHNICAL FIELD

The present application relates to the field of electronics, and more particularly, to methods of forming electronic component packages and related structures.

### BACKGROUND

A Micro Electro Mechanical Systems (MEMS) package typically includes a MEMS sensor die, sometimes called a MEMS electronic component. As the MEMS sensor die receives external stimulus such as sound waves or pneumatic pressure, the variations in the stimulus signals are converted to electrical signals.

The MEMS sensor die is typically covered with a lid to protect the MEMS sensor die. To allow the MEMS sensor die to receive external stimulus, a port is formed in the lid to provide access to the ambient environment. However, the MEMS sensor die can get contaminated by airborne particulates passing through the port thus damaging or destroying the MEMS sensor die.

### BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a cross-sectional view of an array of metal mesh lid MEMS packages during fabrication in accordance with one embodiment;

FIG. 2 is a top perspective view of a metal mesh lid array of the array of FIG. 1 in accordance with one embodiment;

FIG. 3 is top perspective view of a metal mesh lid array in accordance with another embodiment;

FIG. 4 is a perspective view of a metal mesh sheet for use in forming a metal mesh lid array in accordance with one embodiment;

FIG. 5 is a perspective view of a metal mesh cap array formed from the metal mesh sheet of FIG. 4 in accordance with one embodiment;

FIG. 6 is a cross-sectional view of a metal mesh lid array during fabrication with the metal mesh cap array of FIG. 5 in accordance with one embodiment;

FIG. 7 is a cross-sectional view of the metal mesh lid array of FIG. 6 after fabrication in accordance with one embodiment;

FIG. 8 is a cross-sectional view of a metal mesh lid array during fabrication with the metal mesh sheet of FIG. 4 in accordance with one embodiment;

FIG. 9 is a cross-sectional view of the metal mesh lid array of FIG. 8 after fabrication in accordance with one embodiment;

FIG. 10 is a cross-sectional view of a metal mesh lid array during fabrication with the metal mesh cap array of FIG. 5 in accordance with one embodiment;

FIG. 11 is a cross-sectional view of the metal mesh lid array of FIG. 10 at a later stage during fabrication in accordance with one embodiment;

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FIG. 12 is a cross-sectional view of the metal mesh lid array of FIG. 11 at a later stage during fabrication in accordance with one embodiment;

FIG. 13 is a cross-sectional view of a metal mesh lid array formed with the metal mesh cap array of FIG. 5 in accordance with one embodiment;

FIG. 14 is a cross-sectional view of a metal mesh lid array formed with the metal mesh cap array of FIG. 5 in accordance with one embodiment;

FIG. 15 is a cross-sectional view of an array of metal mesh lid leadframe MEMS packages during fabrication in accordance with another embodiment; and

FIG. 16 is a cross-sectional view of a metal mesh lid leadframe MEMS package in accordance with yet another embodiment.

In the following description, the same or similar elements are labeled with the same or similar reference numbers.

### DETAILED DESCRIPTION

As an overview and in accordance with one embodiment, referring to FIG. 1, a metal mesh lid MEMS package 100 includes a substrate 102, a MEMS electronic component 104 coupled to substrate 102, and a metal mesh lid 108 coupled to substrate 102 with a lid adhesive 140. Metal mesh lid 108 includes a lid body 144, e.g., formed of a polymeric material, having a top port 148 formed therein and a metal mesh cap 142 coupled to lid body 144.

Metal mesh cap 142 covers top port 148. Accordingly, metal mesh cap 142 serves as both a particulate filter over the open top port 148, as well as a continuous conductive shield for EMI/RF interferences. Metal mesh cap 142 also provides an acoustic impedance control through selecting the appropriate mesh sizing. Further, metal mesh cap 142 also provides a locking feature for lid adhesive 140 to maximize the attach strength of metal mesh lid 108 to substrate 102.

Now in more detail, FIG. 1 is a cross-sectional view of an array 101 of metal mesh lid Micro Electro Mechanical Systems (MEMS) packages 100 during fabrication in accordance with one embodiment. Each metal mesh lid MEMS package 100 includes a substrate 102, a MEMS electronic component 104, a converter electronic component 106, and a metal mesh lid 108. For simplicity, a single metal mesh lid MEMS package 100 is described below and those of skill in the art will understand that the description is equally applicable to all of the metal mesh lid MEMS packages 100 of array 101.

Substrate 102 includes a dielectric material such as laminate, ceramic, printed circuit board material, or other dielectric material. Formed on an upper, e.g., first, surface 102U of substrate 102 are electrically conductive upper, e.g., first, terminals 110, e.g., formed of copper. Substrate 102 further includes a lower, e.g., second, surface 102L.

Substrate 102 further includes upper, e.g., first, traces 112 formed at upper surface 102U and lower, e.g., second, traces 114 formed at lower surface 102L. Lower traces 114 are electrically connected to upper traces 112 by electrically conductive vias 116 extending through substrate 102 between upper surface 102U and lower surface 102L.

Substrate 102 further includes upper ground terminals 118 formed at upper surface 102U and lower ground lands 120 formed at lower surface 102L. Lower ground lands 120 are electrically connected to upper ground terminals 118 by electrically conductive ground vias 122 extending through substrate 102 between upper surface 102U and lower surface 102L.

Substrate 102 can further include an upper, e.g., first, solder mask at upper surface 102U that protects first portions of

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upper traces **112** while exposing second portions, e.g., upper terminals **110**, of upper traces **112** and exposing upper ground terminals **118**. Substrate **102** can further include a lower, e.g., second, solder mask at lower surface **102L** that protects first portions of lower traces **114** while exposing second portions, e.g., lands **124**, of lower traces **114** and exposing lower ground lands **120**.

In one embodiment, lands **120**, **124** are distributed in an array thus forming a Land Grid Array (LGA). Alternatively, interconnection balls, e.g., solder balls, are formed on lands **120**, **124** thus forming a Ball Grid Array (BGA).

Although a particular electrically conductive pathway is described above, other electrically conductive pathways can be formed. For example, contact metallizations can be formed between the various electrical conductors.

Further, instead of straight through vias **116**, **122**, in one embodiment, substrate **102** is a multilayer substrate and a plurality of vias and/or internal traces form the electrical interconnection between upper traces **112** and lower traces **114** and between upper ground terminals **118** and lower ground lands **120**.

Converter electronic component **106** is a conventional converter electronic component, sometimes called an Application Specific Integrated Circuit (ASIC) chip. Accordingly, the features and functions of converter electronic component **106** are well known to those of skill in the art. Thus, only a general description of various features and functions of converter electronic component **106** are set forth below. Generally, converter electronic component **106** converts the signals(s) from MEMS electronic component **104** as required for the particular application.

Converter electronic component **106** includes an active, e.g., first, surface **106U** and an opposite inactive, e.g., second, surface **106L**. Lower surface **106L** is mounted to upper surface **102U** of substrate **102** with an adhesive **125**. Active surface **106U** includes bond pads **126**.

Bond pads **126** of converter electronic component **106** are electrically connected to respective upper terminals **110** with electrically conductive bond wires **128**.

In accordance with another embodiment, converter electronic component **106** is mounted in a flip chip configuration. Illustratively, flip chip bumps, e.g., solder, forms the physical and electrical interconnection between bond pads **126** of converter electronic component **106** and upper terminals **110** of upper traces **112**. Optionally, an underfill is applied between converter electronic component **106** and substrate **102**.

In accordance with yet another embodiment, metal mesh lid MEMS microphone package **100** is formed without converter electronic component **106**. Illustratively, the functionality of converter electronic component **106** is incorporated into MEMS electronic component **104**. Accordingly, a separate converter electronic component **106** is unnecessary and not provided.

MEMS electronic component **104** is a conventional MEMS microphone electronic component, sometimes called a MEMS chip. Accordingly, the features and functions of MEMS electronic component **104** are well known to those of skill in the art. Thus, only a general description of various features and functions of MEMS electronic component **104** are set forth below. In this embodiment, MEMS electronic component **104** is an acoustical microphone although can be another type of MEMS electronic component such as a pressure sensor as discussed further below.

MEMS electronic component **104** includes a lower, e.g., first, surface **104L** and an opposite upper, e.g., second, surface **104U**. Lower surface **104L** is mounted to upper surface **102U** of substrate **102** with an adhesive **129**. MEMS elec-

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tronic component **104** further includes a moveable compliant diaphragm **130** and bond pads **132** formed at upper surface **104U**. Bond pads **132** are electrically connected to respective upper terminals **110** with electrically conductive bond wires **134**.

Optionally, one or more of bond pads **132** of MEMS electronic component **104** are electrically connected to respective one or more bond pads **126** of converter electronic component **106** with bond wires **134**. Accordingly, bond pads **132** of MEMS electronic component **104** are electrically connected to respective upper terminals **110**, to respective bond pads **126** of converter electronic component **106**, or to both respective upper terminals **110** and respective bond pads **126** of converter electronic component **106**.

MEMS electronic component **104** further includes a rigid perforated backplate **136** at lower surface **104L**. MEMS electronic component **104** further includes an aperture **138** extending through MEMS electronic component **104** and between upper surface **104U** and lower surface **104L**. More particularly, aperture **138** extends between and separates diaphragm **130** and backplate **136** such that diaphragm **130** and backplate **136** form a capacitor.

As described further below, during operation, sound waves (or pressure waves in other embodiments) move diaphragm **130** thus causing changes in the capacitance between diaphragm **130** and backplate **136**. An electrical signal corresponding to the capacitance variations is output on bond pads **132**.

MEMS electronic component **104** and converter electronic component **106** are enclosed within metal mesh lid **108**. Metal mesh lid **108** includes a metal mesh cap **142** and a lid body **144**.

Metal mesh cap **142** is a semi-permeable barrier made of connected strands of metal or other electrically conductive material, e.g., is a metal mesh. Metal mesh cap **142** includes a plurality of small holes **146** through which external stimulus can pass. More particularly, metal mesh cap **142** is permeable to sound and pressure, i.e., sound waves and pneumatic pressure can pass through metal mesh cap **142**.

Lid body **144** is formed of a metal mesh sealing material. Illustratively, lid body **144** is a dielectric material, e.g., is molding compound, encapsulant, adhesive, a polymeric material, or other material that can seal small holes **146** in metal mesh cap **142**. In other embodiments, lid body **144** is an electrically conductive material, e.g., is silver paint, electrically conductive adhesive, or other material that can seal small holes **146** in metal mesh cap **142**.

Generally, lid body **144** is a complete barrier to sound and pressure, i.e., sound waves and pneumatic pressure cannot pass directly through lid body **144**.

Metal mesh lid **108** further includes a top port **148**. Top port **148** is an aperture, sometimes called an opening or hole, extending through metal mesh lid **108**. More particularly, top port **148** is an aperture within lid body **144**. However, top port **148** is covered by metal mesh cap **142**.

More particularly, top port **148** is in fluid communication with a lid cavity **150** of metal mesh lid **108** and thus diaphragm **130** of MEMS electronic component **104** located within lid cavity **150**. As used herein, regions are in fluid communication when they are directly connected to one another without an intervening structure such that fluid, e.g., air, and sound can freely move from one region to the other.

Accordingly, during use, sound travels through top port **148**, passes through small holes **146** in metal mesh cap **142**, through lid cavity **150** and moves diaphragm **130**. As described above, the motion of diaphragm **130** from the sound is converted into an electrical signal that is output on

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bond pads **132**, e.g., through various conductors such as bond pads, interconnects, output pads and/or lead terminals.

As set forth above, top port **148** is covered with metal mesh cap **142**. Metal mesh cap **142** is a filter, sometimes called a filtration structure, that prevents dust, airborne particulates, and other contaminants from passing through top port **148** and entering into lid cavity **150**. In this manner, dust, airborne particulates, and other contamination are prevented from damaging or destroying MEMS electronic component **104**.

Further, through mesh size selection, i.e., through selecting the size of holes **146** of metal mesh cap **142**, the size of foreign materials allowed to pass through metal mesh cap **142** is controlled thereby preventing selective size ranges of damaging particles from passing through top port **148**. In addition, through mesh size selection along with selection of the diameter of top port **148**, acoustic impedance and the resulting performance of MEMS electronic component **104** is controlled for a given application.

Further, top port **148** allows venting and escape of expansive pressure during formation of metal mesh lid MEMS package **100**, e.g., during sealing of metal mesh lid **108** to substrate **102**.

Further, metal mesh cap **142** is formed of an electrically conductive material to provide Radio Frequency (RF) shielding or more generally to provide shielding from ElectroMagnetic Interference (EMI). Metal mesh cap **142** is exposed at a lid base **152** of metal mesh lid **108**.

More particularly, metal mesh lid **108** includes a lid plate **154** parallel to substrate **102**, lid sidewalls **156** extending perpendicularly downward from lid plate **154** and terminating at lid base **152**. Lid plate **154** has top port **148** formed therein. Lid base **152** is a rectangular annulus parallel to upper surface **102U** of substrate **102**. Although the terms parallel, perpendicular, and similar terms are used herein, it is to be understood that the described features may not be exactly parallel and perpendicular, but only substantially parallel and perpendicular to within excepted manufacturing tolerances.

As set forth above, metal mesh cap **142** is exposed at lid base **152**. Lid adhesive **140** bonds lid base **152** and thus metal mesh cap **142** to the outer periphery of upper surface **102U** of substrate **102**. As the surface area of metal mesh cap **142** in contact with lid adhesive **140** is maximized as compared to a flat surface, metal mesh cap **142** enhances bonding of metal mesh lid **108** to substrate **102**.

Further, in accordance with this embodiment, lid adhesive **140** is electrically conductive, e.g., is an electrically conductive epoxy, solder, or other electrically conductive adhesive. Metal mesh lid **108** is mounted to and electrically connected by lid adhesive **140** to upper surface **102U** of substrate **102** including upper ground terminals **118** exposed thereon.

In one embodiment, a reference voltage source, e.g., ground, is provided to upper ground terminals **118** and thus metal mesh lid **108** during operation. Illustratively, lower ground land **120** are coupled to the reference voltage source, e.g., ground, which is thus coupled to upper ground terminals **118**, lid adhesive **140**, and metal mesh cap **142** of metal mesh lid **108**. Stated another way, lower ground lands **120** are grounded thus grounding upper ground terminals **118**, lid adhesive **140**, and metal mesh lid **108**.

Thus, as set forth above, metal mesh cap **142** serves as both a particulate filter over the open top port **148**, as well as a continuous conductive shield for EMI/RF interferences. Metal mesh cap **142** also provides a locking feature for lid adhesive **140** to maximize metal mesh lid **108** attach strength.

Although MEMS electronic component **104** is described above as a MEMS microphone, in other embodiments, MEMS electronic component **104** is another type of MEMS

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device. For example, MEMS electronic component **104** is a pressure sensor or other MEMS electronic component where access to the ambient environment is required or desired.

After fabrication of the plurality of metal mesh lid MEMS packages **100**, array **101** is singulated along singulation streets **158**, e.g., using a saw, laser, or other singulation technique, to form a plurality of individual metal mesh lid MEMS packages **100**. Although metal mesh lid MEMS packages **100** are set forth above as being formed simultaneously in array **101**, in another embodiment, metal mesh lid MEMS packages **100** are formed individually.

FIG. 2 is a top perspective view of a metal mesh lid array **160** of array **101** of FIG. 1 in accordance with one embodiment. Referring now to FIGS. 1 and 2 together, metal mesh lid array **160** includes metal mesh lids **108** integrally connected together. Although a 4x4 array of metal mesh lids **108** is illustrated in FIG. 2, generally metal mesh lid array **200** includes an NxM array or strip of metal mesh lids **108** for use in forming an NxM array or strip of metal mesh lid MEMS packages **100**.

Metal mesh lid array **160** includes an upper, e.g., first, surface **160U** and an opposite lower, e.g., second, surface **160L**. Lower surface **160L** is mounted to substrates **102** by lid adhesives **140**.

Gaps **162**, e.g., in a criss-cross pattern, are formed in upper surface **160U** between adjacent metal mesh lids **108**, e.g., to facilitate singulation of metal mesh lid MEMS packages **100**.

FIG. 3 is top perspective view of a metal mesh lid array **160A** in accordance with another embodiment. Metal mesh lid array **160A** of FIG. 3 is similar to metal mesh lid array **160** of FIG. 2 except that gaps **162** (see FIGS. 1, 2) are not formed but are filled with lid body **144** in accordance with the embodiment illustrated in FIG. 3. Accordingly, upper surface **160U** of metal mesh lid array **160A** of FIG. 3 is a continuous flat plane having top ports **148** formed therein.

FIG. 4 is a perspective view of a metal mesh sheet **400** for use in forming a metal mesh lid array in accordance with one embodiment. Metal mesh sheet **400** is a sheet of metal mesh having small holes **146** formed therein. Metal mesh sheet **400** is sometimes called a fine mesh.

Generally, small holes **146** are sufficiently large to allow sound or other desired stimulus to pass through metal mesh sheet **400**. However, small holes **146** are sufficiently small to prevent dust, airborne particulates, or other contaminants from passing through metal mesh sheet **400** and to provide sufficient EMI shielding.

FIG. 5 is a perspective view of a metal mesh cap array **500** formed from metal mesh sheet **400** of FIG. 4 in accordance with one embodiment. Referring to FIGS. 4 and 5 together, metal mesh sheet **400** is shaped from the flat sheet of FIG. 4 into metal mesh cap array **500** as illustrated in FIG. 5. Illustratively, metal mesh sheet **400** is shaped by being pressed into a form or using other mechanical shaping techniques to form metal mesh cap array **500** as illustrated in FIG. 5. Metal mesh cap array **500** is sometimes called a pre-formed mesh array.

Referring now to FIG. 5, metal mesh cap array **500** includes a plurality of metal mesh caps **142** integrally connected together. Each metal mesh cap **142** includes a metal mesh cap plate **502**, metal mesh cap sidewalls **504** extending perpendicularly downward from metal mesh cap plate **502** and terminating at a metal mesh cap base **506**.

FIG. 6 is a cross-sectional view of a metal mesh lid array **160B** during fabrication with metal mesh cap array **500** of FIG. 5 in accordance with one embodiment. Note that metal mesh cap array **500** is inverted (upside down) in the view of FIG. 6 as compared to the view in FIG. 5.

Referring now to FIG. 6, a lid body array 600 is formed, e.g., by molding or other technique. Lid body array 600 includes a plurality of lid bodies 144 integrally connected together. Lid body array 600 is sometimes called a lid array.

Each lid body 144 includes a lid body plate 602 having a top port 148 formed therein. Each lid body 144 further includes lid body sidewalls 604 extending perpendicularly from lid body plate 602 and terminating at a lid body base 606.

Each lid body 144 corresponds in shape to the respective metal mesh cap 142. More generally, lid body array 600 corresponds in shape to metal mesh cap array 500 allowing metal mesh cap array 500 to be bonded to lid body array 600.

A metal mesh cap bonding material 608 is applied to lid body array 600 and more particularly to lid body plates 602, lid body sidewalls 604, and lid body bases 606. Metal mesh cap bonding material 608 is an adhesive material, e.g., epoxy.

Metal mesh cap array 500 is moved as indicated by the arrow 610 into contact with metal mesh cap bonding material 608 and thus bonded to lid body array 600 to form metal mesh lid array 160B as illustrated in FIG. 7. In one embodiment, metal mesh cap array 500 is held in place as metal mesh cap bonding material 608 cures.

FIG. 7 is a cross-sectional view of metal mesh lid array 160B of FIG. 6 after fabrication in accordance with one embodiment. As illustrated in FIG. 7, metal mesh lid array 160B includes metal mesh caps 142 bonded to lid bodies 144 by metal mesh cap bonding material 608 to form metal mesh lids 108. Top ports 148 extend through lid bodies 144 yet are covered by metal mesh caps 142.

Metal mesh cap plates 502 and lid body plates 602 including metal mesh cap bonding material 608 therebetween collectively define lid plates 154 of metal mesh lids 108. Metal mesh cap sidewalls 504 and lid body sidewalls 604 including metal mesh cap bonding material 608 therebetween collectively define lid sidewalls 156 of metal mesh lids 108. Metal mesh cap bases 506 and lid body bases 606 including metal mesh cap bonding material 608 therebetween collectively define lid bases 152 of metal mesh lids 108.

FIG. 8 is a cross-sectional view of a metal mesh lid array 160C during fabrication with metal mesh sheet 400 of FIG. 4 in accordance with one embodiment. Referring now to FIG. 8, lid body array 600 is placed within a hot forming press 800. Lid body array 600 is described above regarding FIGS. 6, 7 and so the description thereof is not repeated here for simplicity.

More particularly, lid body array 600 is placed on and supported by a lower hot press plate 802 of hot forming press 800. Metal mesh sheet 400 is placed above lid body array 600 as illustrated in FIG. 8. An upper hot press plate 804 of hot forming press 800 is moved as indicated by the direction of arrow 806 to simultaneously shape metal mesh sheet 400 into metal mesh cap array 500 while simultaneously bonding metal mesh cap array 500 to lid body array 600.

More particularly, upper hot press plate 804 includes a plurality of metal mesh cap shaping forms 808 protruding downward from upper hot press plate 804. Metal mesh cap shaping forms 808 correspond in shape with lid bodies 144 of lid body array 600.

Metal mesh cap shaping forms 808 press metal mesh sheet 400 into lid bodies 144 of lid body array 600. In one embodiment, hot forming press 800 is heated. Due to the heat and pressure, metal mesh sheet 400 is shaped into metal mesh cap array 500. At the same time, due to the heat and pressure, lid body array 600 is deformed, e.g., slightly liquefied, to bond to metal mesh cap array 500 to form metal mesh lid array 160C as illustrated in FIG. 9.

FIG. 9 is a cross-sectional view of metal mesh lid array 160C of FIG. 8 after fabrication in accordance with one embodiment. As illustrated in FIG. 9, metal mesh lid array 160C includes metal mesh caps 142 directly bonded to lid bodies 144 to form metal mesh lids 108. Top ports 148 extend through lid bodies 144 yet are covered by metal mesh caps 142.

Metal mesh cap plates 502 and lid body plates 602 collectively define lid plates 154 of metal mesh lids 108. Metal mesh cap sidewalls 504 and lid body sidewalls 604 collectively define lid sidewalls 156 of metal mesh lids 108. Metal mesh cap bases 506 and lid body bases 606 collectively define lid bases 152 of metal mesh lids 108.

FIG. 10 is a cross-sectional view of a metal mesh lid array 160D during fabrication with metal mesh cap array 500 of FIG. 5 in accordance with one embodiment. Referring now to FIG. 10, top port plugs 1002 are formed in metal mesh cap plates 502 of metal mesh caps 142. Top port plugs 1002 are formed in top port hole areas corresponding to the final location of top ports 148 as described further below. Illustratively, top port plugs 1002 are formed of a removable material such as wax.

FIG. 11 is a cross-sectional view of metal mesh lid array 160D of FIG. 10 at a later stage during fabrication in accordance with one embodiment. Referring now to FIG. 11, lid body array 600 is formed on metal mesh cap array 500.

In one embodiment, lid body array 600 is a sealed shell formed on metal mesh cap array 500. In various embodiments, lid body array 600 is formed by spraying or printing a material such as silver paint or epoxy on metal mesh cap array 500. In another embodiment, lid body array 600 is formed by dipping metal mesh cap array 500 into a material such as silver paint or epoxy.

In one embodiment, lid body array 600 covers top port plugs 1002. However, in another embodiment, top port plugs 1002 are not covered by lid body array 600. For example, top port plugs 1002 are not wettable by the material of lid body array 600 and thus are not covered.

FIG. 12 is a cross-sectional view of metal mesh lid array 160D of FIG. 11 at a later stage during fabrication in accordance with one embodiment. Referring now to FIGS. 11 and 12 together, top port plugs 1002 and any of lid body array 600 formed thereon are removed to form top ports 148.

In one embodiment, top port plugs 1002 are removed by heating metal mesh lid array 160D to melt top port plugs 1002. In another embodiment, top port plugs 1002 are removed by chemical etching or other removal technique.

As illustrated in FIG. 12, metal mesh lid array 160D includes metal mesh caps 142 directly bonded to lid bodies 144 to form metal mesh lids 108. Top ports 148 extend through lid bodies 144 yet are covered by metal mesh caps 142.

Metal mesh cap plates 502 and lid body plates 602 collectively define lid plates 154 of metal mesh lids 108. Metal mesh cap sidewalls 504 and lid body sidewalls 604 collectively define lid sidewalls 156 of metal mesh lids 108. Metal mesh cap bases 506 and lid body bases 606 collectively define lid bases 152 of metal mesh lids 108.

FIG. 13 is a cross-sectional view of a metal mesh lid array 160E formed with metal mesh cap array 500 of FIG. 5 in accordance with one embodiment. Referring now to FIG. 13, lid body array 600 is molded to metal mesh cap array 500. Illustratively, metal mesh cap array 500 is insert molded, e.g., is placed inside of an injection mold, material of lid body array 600, e.g., Liquid Crystal Polymer (LCP) or other high temperature polymer, is injected into the injection mold

around metal mesh cap array **500**, followed by removal of metal mesh lid array **160E** from the injection mold.

As illustrated in FIG. **13**, metal mesh lid array **160E** includes metal mesh caps **142** directly bonded to lid bodies **144** to form metal mesh lids **108**. Top ports **148** extend through lid bodies **144** yet are covered by metal mesh caps **142**. Metal mesh cap plates **502** and lid body plates **602** collectively define lid plates **154** of metal mesh lids **108**. Metal mesh cap sidewalls **504** and lid body sidewalls **604** collectively define lid sidewalls **156** of metal mesh lids **108**. Metal mesh cap bases **506** and lid body bases **606** collectively define lid bases **152** of metal mesh lids **108**.

As illustrated in FIG. **13**, metal mesh cap array **500** is at or near the inner surface **1302** of lid body array **600**. However, in another embodiment such as that illustrated in FIG. **14**, metal mesh cap array **500** is embedded within lid body array **600**.

FIG. **14** is a cross-sectional view of a metal mesh lid array **160F** formed with metal mesh cap array **500** of FIG. **5** in accordance with one embodiment. Referring now to FIG. **14**, lid body array **600** is molded to metal mesh cap array **500** in a manner similar to that described above regarding FIG. **13**.

As illustrated in FIG. **14**, metal mesh lid array **160F** includes metal mesh caps **142** directly bonded to lid bodies **144** to form metal mesh lids **108**. Top ports **148** extend through lid bodies **144** yet are covered by metal mesh caps **142**. Metal mesh cap plates **502** and lid body plates **602** collectively define lid plates **154** of metal mesh lids **108**. Metal mesh cap sidewalls **504** and lid body sidewalls **604** collectively define lid sidewalls **156** of metal mesh lids **108**. Metal mesh cap bases **506** and lid body bases **606** collectively define lid bases **152** of metal mesh lids **108**.

However, in accordance with this embodiment, metal mesh cap array **500** is embedded within lid body array **600**. More particularly, lid body array **600** exists between inner surface **1302** of lid body array **600** and metal mesh cap array **500**. Further, lid body array **600** exists between an outer surface **1402** of lid body array **600** and metal mesh cap array **500**.

However, metal mesh cap bases **506** are exposed from lid body bases **606**. This facilitates formation of electrical interconnection with metal mesh cap bases **506** and thus metal mesh caps **142**, e.g., for grounding.

Thus, as set forth above in regards to FIG. **6-14**, metal mesh cap array **500** forms an inlay or embedded layer within lid body array **600**, e.g., a polymer lid array.

FIG. **15** is a cross-sectional view of an array **1501** of metal mesh lid leadframe MEMS packages **1500** during fabrication in accordance with another embodiment. Array **1501** of FIG. **15** is similar to array **101** of FIG. **1** except that array **1501** of FIG. **15** is formed with leadframes **1502** instead of substrates **102** of array **101** of FIG. **1** as discussed further below.

Referring now to FIG. **15**, in accordance with this embodiment, each metal mesh lid leadframe MEMS package **1500** includes a leadframe **1502**, MEMS electronic component **104**, converter electronic component **106**, and metal mesh lid **108**. For simplicity, a single metal mesh lid leadframe MEMS package **1500** is described below and those of skill in the art will understand that the description is equally applicable to all of the metal mesh lid leadframe MEMS packages **1500** of array **1501**.

Leadframe **1502** includes a die paddle **1504**, leads **1506**, and a mold compound **1508**. Die paddle **1504** and leads **1506** are formed of an electrically conductive material, e.g., copper, plated copper, or other electrically conductive material. Mold compound **1508** is a dielectric material that holds die paddle **1504** and leads **1506** together.

Lower surface **106L** of converter electronic component **106** is mounted to die paddle **1504** of leadframe **1502** with

adhesive **125**. Bond pads **126** of converter electronic component **106** are electrically connected to respective leads **1506** of leadframe **1502** with bond wires **128**.

Lower surface **104L** of MEMS electronic component **104** is mounted to die paddle **1504** of leadframe **1502** with adhesive **129**. Bond pads **132** are electrically connected to respective leads **1506** of leadframe **1502** and/or respective one or more bond pads **126** of converter electronic component **106** with bond wires **134**.

MEMS electronic component **104** and converter electronic component **106** are enclosed within metal mesh lid **108**. More particularly, metal mesh lid **108** is mounted to leads **1506** and mold compound **1508** of leadframe **1502** with a lid adhesive **1540**. Lid adhesive **1540** is a dielectric material in one embodiment to prevent shorting of metal mesh lid **108** with leads **1506**. However, in another embodiment, one or more electrical connections are formed between metal mesh lid **108** and leads **1506**, e.g., by selective application of an electrically conductive material such as epoxy.

After fabrication of the plurality of metal mesh lid leadframe MEMS packages **1500**, array **1501** is singulated along singulation streets **158**, e.g., using a saw, laser, or other singulation technique, to form a plurality of individual metal mesh lid leadframe MEMS packages **1500**. Accordingly, leads **1506** do not project outward beyond the sides of metal mesh lid leadframe MEMS packages **1500** in this embodiment.

FIG. **16** is a cross-sectional view of a metal mesh lid leadframe MEMS package **1600** in accordance with yet another embodiment. Metal mesh lid leadframe MEMS package **1600** of FIG. **16** is similar to metal mesh lid leadframe MEMS package **1500** of FIG. **15** except that leads **1506** project outward past sides **1610** of metal mesh lid leadframe MEMS package **1600** of FIG. **16**.

Further, in accordance with one embodiment, metal mesh lid **108** is mounted to leadframe **1502** individually, e.g., after singulation from a metal mesh lid array such as any one of those described above.

Although specific embodiments were described herein, the scope of the invention is not limited to those specific embodiments. Numerous variations, whether explicitly given in the specification or not, such as differences in structure, dimension, and use of material, are possible. The scope of the invention is at least as broad as given by the following claims.

What is claimed is:

1. A structure comprising:

a substrate;

a Micro Electro Mechanical Systems (MEMS) electronic component coupled to the substrate; and

a metal mesh lid coupled to the substrate, the metal mesh lid comprising:

a polymeric lid body having a top port formed therein; and

a metal mesh cap embedded within the polymeric lid body, wherein the metal mesh cap covers the top port such that air may flow through the top port.

2. The structure of claim 1 wherein the metal mesh lid further comprises: a lid plate parallel to the substrate; and lid sidewalls extending perpendicularly from the lid plate and terminating at a lid base of the metal mesh lid.

3. The structure of claim 2 wherein the metal mesh cap is exposed from the polymeric lid body at the lid base.

4. The structure of claim 1 wherein the metal mesh cap comprises connected strands of electrically conductive material.



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5. The structure of claim 4 wherein the metal mesh cap comprises holes therein through which external stimulus can pass.

6. The structure of claim 5 wherein the polymeric lid body seals the holes of the metal mesh cap.

7. The structure of claim 1 wherein the metal mesh cap forms a filtration structure that prevents contaminants from passing through the top port.

8. The structure of claim 1 further comprising a lid adhesive coupling the metal mesh lid to the substrate, wherein the metal mesh cap forms a locking feature for the lid adhesive.

9. The structure of claim 1 further comprising an electrically conductive lid adhesive coupling the metal mesh cap to ground terminals of the substrate.

10. A structure comprising:

a metal mesh lid array comprising:

a polymeric lid body array comprising lid bodies having top ports formed therein; and

a metal mesh cap array embedded within the polymeric lid body array, wherein metal mesh caps of the metal mesh cap array cover the top ports such that air may flow through the top ports.

11. The structure of claim 10 wherein the polymeric lid body array further exists between an inner surface of the polymeric lid body array and the metal mesh cap array.

12. The structure of claim 10 further comprising: substrates coupled to the metal mesh lid array.

13. The structure of claim 12 further comprising Micro Electro Mechanical Systems (MEMS) electronic components coupled to the substrates.

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14. The structure of claim 12 wherein the metal mesh lid array further comprises:

lid plates parallel to the substrates; and

lid sidewalls extending perpendicularly from the lid plates and terminating at lid bases of the metal mesh lid array.

15. The structure of claim 14 wherein the metal mesh cap array is exposed from the polymeric lid body array at the lid bases.

16. The structure of claim 14 further comprising a lid adhesive coupling the lid bases to the substrates.

17. The structure of claim 16 wherein the lid adhesive is electrically conductive.

18. A method comprising:

forming a metal mesh cap array comprising metal mesh caps; and

embedding the metal mesh cap array within a polymeric lid body array to form a metal mesh lid array, the polymeric lid body array comprising lid bodies having top ports formed therein, wherein the metal mesh caps cover the top ports such that air may flow through the top ports.

19. The method of claim 18 wherein the embedding comprises: molding the polymeric lid body array to the metal mesh cap array.

20. The method of claim 18 wherein the polymeric lid body array further exists between an inner surface of the polymeric lid body array and the metal mesh cap array.

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